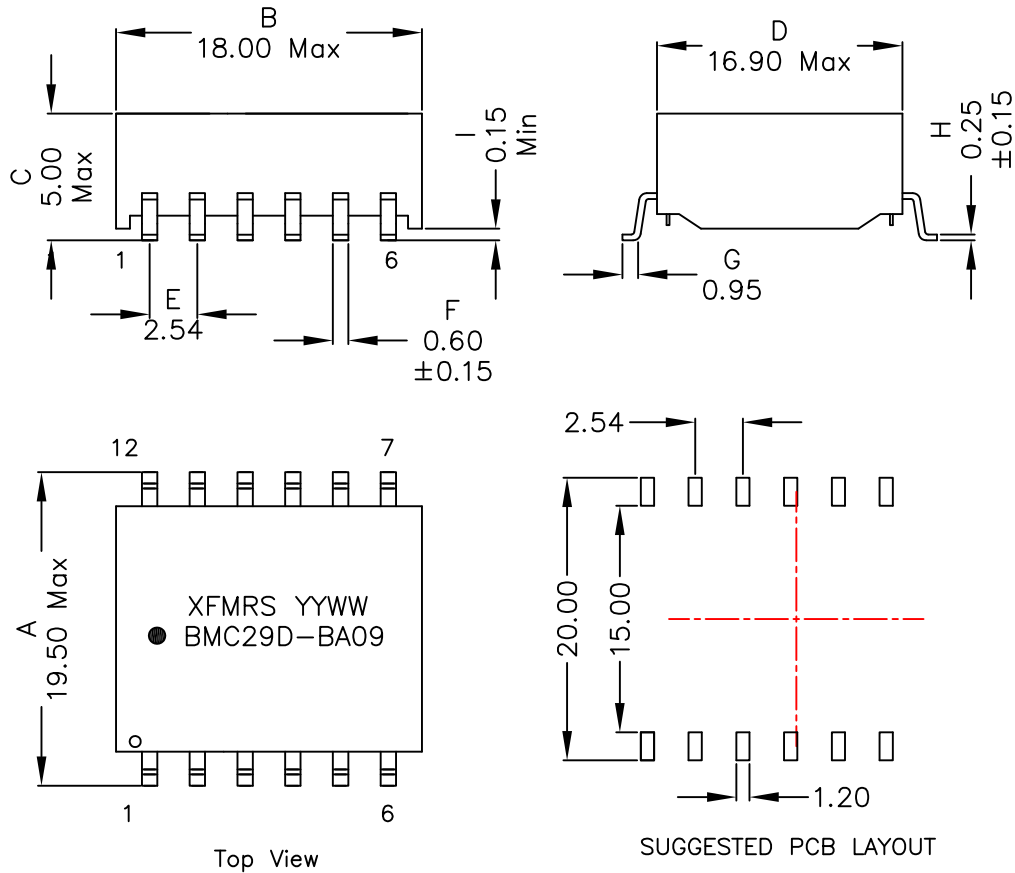
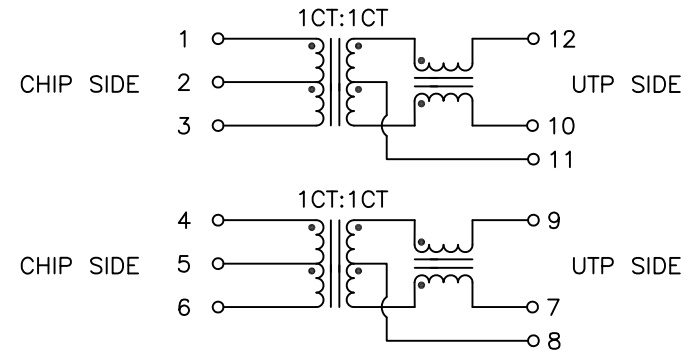


## 1. Mechanical Dimensions:



## 2. Schematic:



## 3. Electrical Specifications: @25°C

UTP Impedance: 100 OHMS  
 Turns Ratio: (CHIP : UTP)=1CT:1CT±2%  
 Isolation Voltage: 2900Vac, CHIP SIDE to UTP SIDE  
 UTP Side OCL: 350uH Min @100KHz 0.1V, 8mA dc  
 UTP Side Q: 8 Min @100KHz 0.1V,  
 Rise Time (10–90%): 4.0ns Typical  
 Insertion Loss (1–50MHz): -1.0dB Maximum  
 (50–100MHz): -2.0dB Maximum  
 Return Loss: 30MHz 60MHz 80MHz  
 -20dB -14dB -11.5dB Typ  
 CMRR: 30MHz 50MHz 100MHz  
 -42dB -37dB -33dB Typ

### Notes:

- Solderability: Leads shall meet MIL-STD-202G, Method 208H for solderability.
- Flammability: UL94V-0
- ASTM oxygen index: > 28%
- Insulation System: Class F 155°C. UL file E151556
- Operating Temperature : -40°C to +85°C
- Storage Temperature Range: -55°C to +125°C
- Aqueous wash compatible
- SMD Lead Coplanarity: 0.004"(0.102mm) Max
- Electrical and mechanical specifications 100% tested
- RoHS Compliant Component
- Recommended IR Reflow peak temp of 245°C Max.

DOC. REV: B/2

<b>XFMRs Inc</b> www.XFMRS.com	Title: TRANSFORMER		
	UNLESS OTHERWISE SPECIFIED TOLERANCES: .xx ±0.25 Dimensions in MM	P/N: XFBMC29D-BA09-A	REV. B
SHEET 1 OF 1	DWN.	Huo	Jan-25-19
	CHK.	YK Liao	Jan-25-19
	APP.	BSJ	Jan-25-19